

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	53858	("205"/\$.ccls. "204"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:13
S2	1836	("205"/125-126,183-184,187,223.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:14
S3	772	("205"/125-126,183-184,187,223.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:14
S4	566	("205"/125-126,183-184,187,223.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:15
S5	6	("205"/125-126,183-184,187,223.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and temperature and flash near etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:30
S6	8	("205"/125-126,183-184,187,223.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and flash near etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:33
S7	2242	("205"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:34
S8	1932	("205"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:35

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S9	16	("205"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and flash near etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:35
S10	33	("205"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and flash near7 etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 13:50
S11	28	("216"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and flash near7 etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:04
S12	30	("438"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and flash near7 etch\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:02
S13	106	("216"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and ((chemical liquid) near10 etch\$3) same temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:06
S14	23	("216"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and (copper with ((chemical liquid) near10 etch\$3)) same temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:18
S15	96	("216"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and ((chemical liquid) near10 etch\$3) and low with temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:20
S16	18	("216"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and ((chemical liquid) near10 etch\$3) and low with temperature and hydrogen near peroxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:24

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S17	16	("216"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and ((chemical liquid) near10 etch\$3) and low near5 temperature and hydrogen near peroxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:36
S18	7	("205"/\$.ccls.) and (electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and ((chemical liquid) near10 etch\$3) and low near5 temperature and hydrogen near peroxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:39
S19	113	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and ((chemical liquid) near10 etch\$3) and low near5 temperature and hydrogen near peroxide not S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:40
S20	0	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and ((chemical liquid) near10 etch\$3) and (low near5 temperature) same (hydrogen near peroxide) not S17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:40
S21	6	(electrolysis electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and ((board printed) near4 circuit) and copper and ((chemical liquid) near10 etch\$3) same (low near5 temperature) and (hydrogen near peroxide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/17 14:41